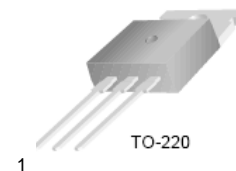


# MBR20200CT

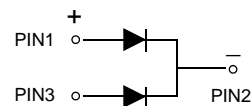
## Dual High Voltage Schottky Rectifier

### Features:

- Low Forward Voltage Drop
- Low Power Loss and High Efficiency
- High Surge Capability
- Rohs Compliant
- Matte Tin(Sn) Lead Finish
- Terminal Leads Surface is Corrosion Resistant and can withstand to 260°C
- Wave Soldering or per MIL-STD-750 Method 2026.



Mark : MBR20200CT



### Absolute Maximum Ratings\* $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Unit
$V_{RRM}$	Maximum Repetitive Reverse Voltage	200	V
$V_R$	Maximum DC Reverse Voltage	200	V
$I_{F(AV)}$	Average Rectified Forward Current, $T_c=115^\circ\text{C}$	10 (Per Leg) 20(Per Device)	A
$I_{FSM}$	Peak Forward Surge Current, 8.3ms Half Sine wave	150	A
$T_{STG}$	Storage Temperature Range	-55 ~ 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature	150	$^\circ\text{C}$

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### Thermal Characteristics\* $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case per Leg	1.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient per Leg	62.5	$^\circ\text{C/W}$

\* MIL standard 883-1012 & JESD51-10

### Electrical Characteristics\* $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Unit
$I_R$	Reverse Current	$V_R=200\text{V}$ $T_C = 25^\circ\text{C}$ $V_R=200\text{V}$ $T_C = 125^\circ\text{C}$		0.2 5	mA
$V_F$	Forward Voltage	$I_F=10\text{A}$ $T_C = 25^\circ\text{C}$ $I_F=10\text{A}$ $T_C = 125^\circ\text{C}$ $I_F=20\text{A}$ $T_C = 25^\circ\text{C}$ $I_F=20\text{A}$ $T_C = 125^\circ\text{C}$		0.9 0.8 1.0 0.9	V

\* DC Item are tested by Pulse Test : Pulse Width $\leq$ 300us, Duty Cycle $\leq$ 2%

Typical Performance Characteristics

Figure 1. Forward Current Characteristics

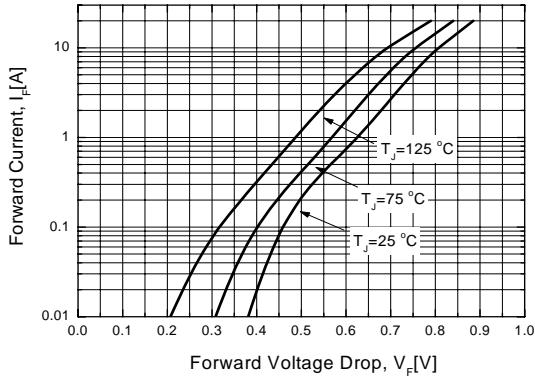


Figure 2. Reverse Leakage Current

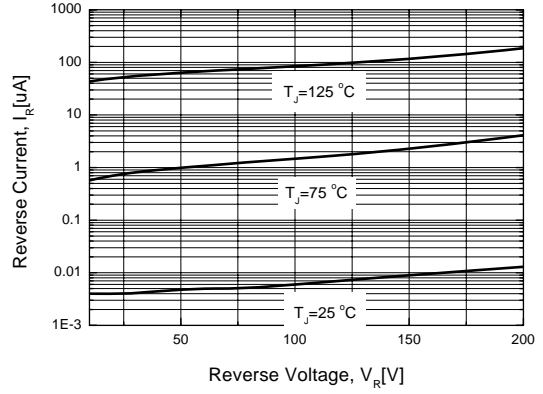


Figure 3. Junction Capacitance

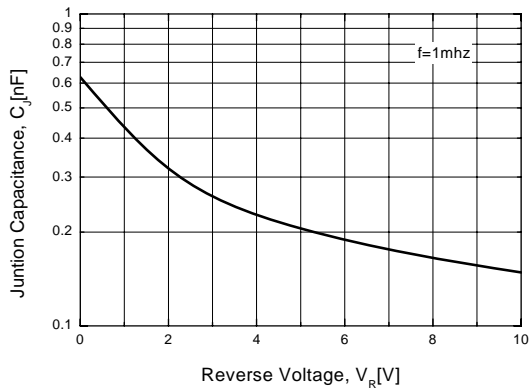
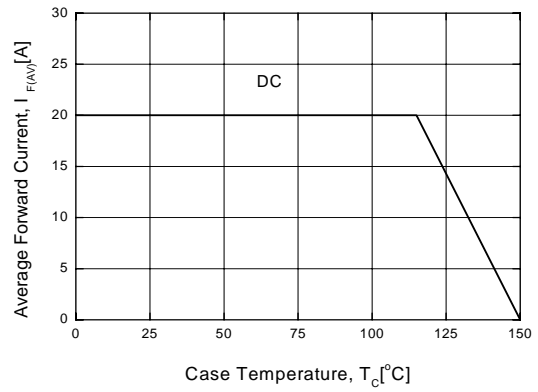


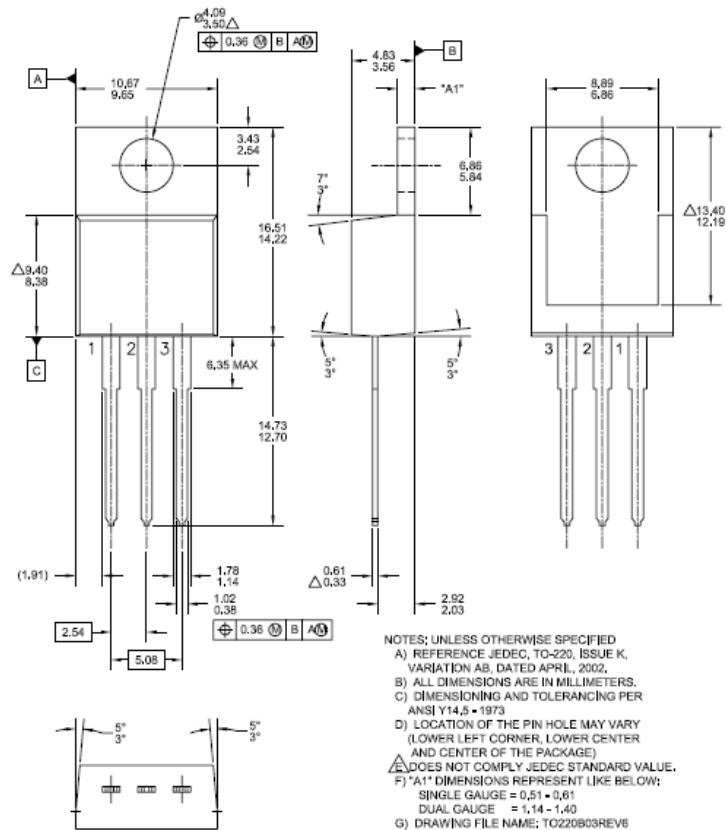
Figure 4. Power Derating



# Package Dimensions

## TO-220(DUAL GAUGE)

Dimensions are in mm






NOTES; UNLESS OTHERWISE SPECIFIED  
 A) REFERENCE JEDEC, TO-220, ISSUE K, VARIATION AB, DATED APRIL, 2002.  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.  
 C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1973  
 D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE)  
 $\Delta$  DOES NOT COMPLY JEDEC STANDARD VALUE.  
 F) "A1" DIMENSIONS REPRESENT LIKE BELOW:  
 SINGLE GAUGE = 0.51 - 0.61  
 DUAL GAUGE = 1.14 - 1.40  
 G) DRAWING FILE NAME: TO220B03REV6

Dimensions in Millimeters



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CTL™	IntelliMAX™	Programmable Active Droop™	TinyBoost™
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FACT®	Motion-SPM™	SPM®	µSerDes™
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FPS™		SuperSOT™-3	VCX™
FRFET®	PDP-SPM™	SuperSOT™-6	
Global Power Resource <sup>SM</sup>	Power220®		

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.